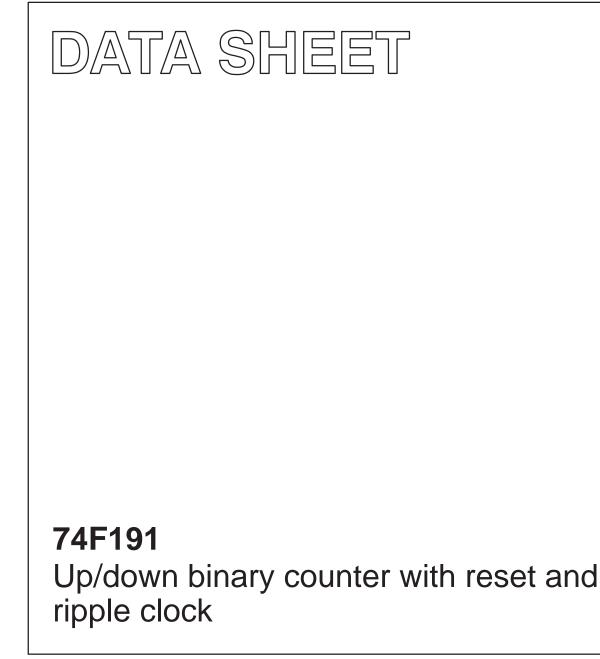
# INTEGRATED CIRCUITS



Product specification

1995 Jul 17

IC15 Data Handbook



HILIP

74F191

#### **FEATURES**

- High speed –125MHz typical f<sub>MAX</sub>
- Synchronous, reversible counting
- 4-Bit binary
- Asynchronous parallel load capability
- Cascadable without external logic
- Single up/down control input

#### DESCRIPTION

The 74F191 is a 4-bit binary counter. It contains four edge-triggered master/slave flip-flops with internal gating and steering logic to provide asynchronous preset and synchronous count-up and count-down operations.

Asynchronous parallel load capability permits the counter to be preset to any desired number. Information present on the parallel data inputs ( $D_0 - D_3$ ) is loaded into the counter and appears on the outputs when the Parallel Load (PL) input is Low. This operation overrides the counting function. Counting is inhibited by a High level on the count enable (CE) input. When CE is Low, internal state changes are initiated. Overflow/underflow indications are provided by two types of outputs, the Terminal Count (TC) and Ripple Clock (RC).

The TC output is normally Low and goes High when: 1) the count reaches zero in the countdown mode or 2) reaches "15" in the count up mode. The TC output will remain High until a state change occurs, either by counting or presetting, or until  $\overline{U}/D$  is changed. TC output should not be used as a clock signal because it is subject to decoding spikes. The TC signal is used internally to enable the  $\overline{RC}$  output. When TC is High and  $\overline{CE}$  is Low, the  $\overline{RC}$  follows the clock pulse. The  $\overline{RC}$  output essentially duplicates the Low clock pulse width, although delayed in time by two gate delays.

### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D <sub>0</sub> - D <sub>3</sub>	Data inputs	1.0/1.0	20µA/0.6mA
CE	Count enable input (active Low)	1.0/3.0	20µA/1.8mA
СР	Clock pulse input (active rising edge)	1.0/1.0	20µA/0.6mA
PL	Asynchronous parallel load control input (active Low)	1.0/1.0	20µA/0.6mA
Ū/D	Up/down count control input	1.0/1.0	20µA/0.6mA
Q <sub>0</sub> - Q <sub>3</sub>	Flip-flop outputs	50/33	1.0mA/20mA
RC	Ripple clock output (active low)	50/33	1.0mA/20mA
TC	Terminal count output	50/33	1.0mA/20mA

NOTE: One (1.0) FAST Unit Load (U.L.) is defined as: 20µA in the High state and 0.6mA in the Low state.

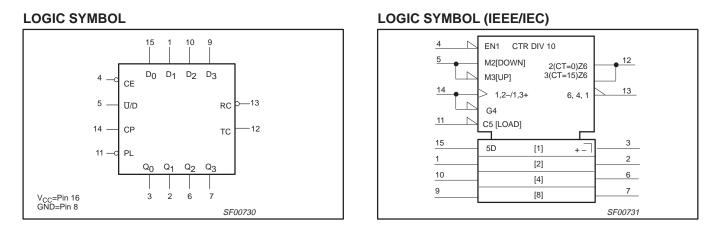
#### **PIN CONFIGURATION** 16 VCC D<sub>1</sub> 1 15 D<sub>0</sub> Q1 2 14 CP Q0 3 CE 4 13 RC U/D 5 12 TC 11 PL Q2 6 Q3 7 10 D<sub>2</sub> GND 8 9 D3 SF00729

TYPE	TYPICAL f <sub>MAX</sub>	TYPICAL SUPPLY CURRENT (TOTAL)
74F191	125MHz	40mA

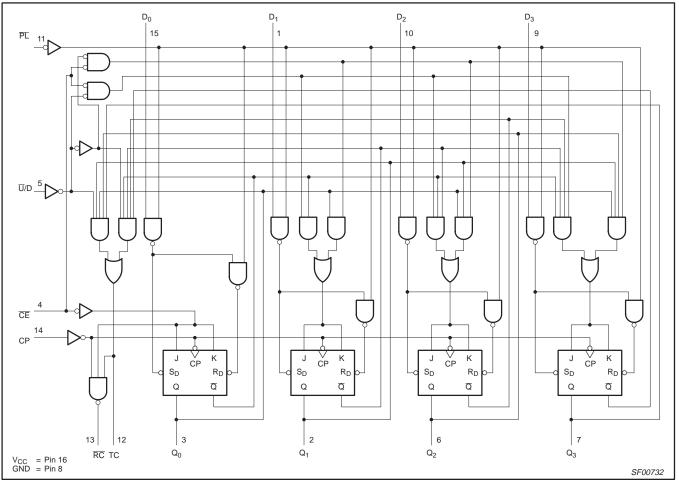
#### **ORDERING INFORMATION**

DESCRIPTION	$\begin{array}{l} \text{COMMERCIAL RANGE} \\ \text{V}_{\text{CC}} = 5\text{V} \pm 10\%, \\ \text{T}_{\text{amb}} = 0^{\circ}\text{C to} + 70^{\circ}\text{C} \end{array}$	PKG DWG #		
16-pin plastic DIP	N74F191N	SOT38-4		
16-pin plastic SO	N74F191D	SOT109-1		

# 74F191



### LOGIC DIAGRAM



74F191

### **MODE SELECT — FUNCTION TABLE**

	INPUTS				OUTPUTS	OPERATING MODE
PL	Ū/D	CE	СР	D <sub>n</sub>	Q <sub>n</sub>	
L	X X	X X	X X	L H	L H	Parallel load
Н	L	I	$\uparrow$	Х	Count up	Count up
Н	Н	I	$\uparrow$	Х	Count down	Count down
н	Х	Н	Х	Х	No change	Hold (do nothing)

### TC AND RC FUNCTION TABLE

	INPUTS			TERMINAL C	OUNT STATE		OUTPUTS		
Ū/D	CE	СР	Q <sub>0</sub>	Q <sub>0</sub> Q <sub>1</sub> Q <sub>2</sub> Q <sub>3</sub>		TC	RC		
н	Н	Х	Н	Н	Н	Н	L	Н	
L	н	х	н	н	н	н	н	н	
L	L	ъ	н	н	н	н	н	ъ	
L	н	Х	L	L	L	L	L	н	
н	н	Х	L	L	L	L	Н	н	
н	L	U	L	L	L	L	Н	ប	

H = High voltage level steady state L = Low voltage level steady state

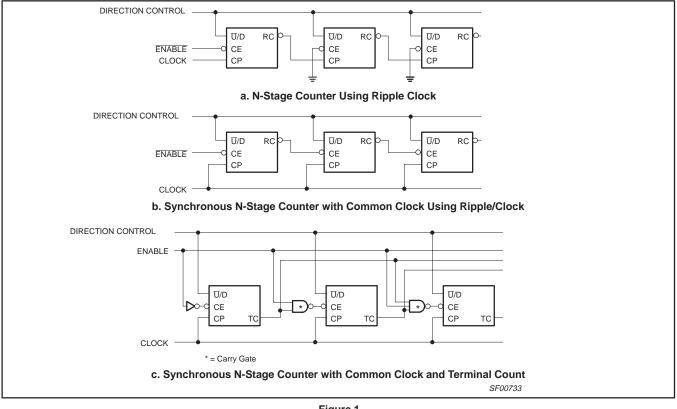
X = Don't care

└ = Low pulse

 $\begin{array}{l} \uparrow \\ = \\ \text{Low-to-High clock transition} \\ \text{I} \\ = \\ \text{Low voltage level one set-up time prior to the Low-to-High clock transition} \end{array}$ 

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#### **APPLICATIONS**





The 74F191 simplifies the design of multi-stage counters, as indicated in Figure 1, each RC output is used as the clock input for the next higher stage. When the clock source has a limited drive capability this configuration is particularly advantageous, since the clock source drives only the first stage. It is only necessary to inhibit the first stage to prevent counting in all stages, since a High signal on CE inhibits the RC output pulse as indicated in the Mode Select Table. The timing skew between state changes in the first and last stages is represented by the cumulative delay of the clock as it ripples through the preceding stages. This is a disadvantage of the configuration in some applications.

Figure 1b shows a method of causing state changes to occur simultaneously in all stages. The RC output signals propagate in ripple fashion and all clock inputs are driven in parallel. The Low state duration of the clock in this configuration must be long enough to allow the negative-going edge of the  $\overline{RC}$  signal to ripple through to the last stage before the clock goes High. Since the RC output of any package goes High shortly after its clock input goes High, there is no such restriction on the High state duration of the clock.

In Figure 1c, the configuration shown avoids ripple delays and their associated restrictions. The combined TC signals from all the preceding stages forms the  $\overline{CE}$  input signal for a given stage. An enable signal must also be included in each carry gate in order to inhibit counting. The TC output of a given stage is not affected by its own CE, therefore, the simple inhibit scheme of Figure 1a and 1b does not apply.

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#### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5.0	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	–0.5 to +V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	40	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature	-65 to +150	٥C

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER		UNIT			
STMBOL	PARAMEIER	Min	Nom	Max	UNIT	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V	
V <sub>IH</sub>	High-level input voltage	2.0			V	
V <sub>IL</sub>	Low-level input voltage			0.8	V	
I <sub>IK</sub>	Input clamp current			-18	mA	
I <sub>OH</sub>	High-level output current			-1	mA	
I <sub>OL</sub>	Low-level output current			20	mA	
T <sub>amb</sub>	Operating free-air temperature range	0		70	٥C	

#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

CVMDOL	DADAMET	- 0			LINUT			
SYMBOL	PARAMET	ER	TEST CONDITIO	Min	Typ <sup>2</sup>	Max	UNIT	
Maria			$V_{CC} = Min, V_{IL} = Max,$	$\pm 10\% V_{CC}$	2.5			V
V <sub>OH</sub>	High-level output voltage		· · · · · · · · · ·	$\pm 5\% V_{CC}$	2.7	3.4		V
M			V <sub>CC</sub> = Min, V <sub>IL</sub> = Max,	$\pm 10\% V_{CC}$		0.30	0.50	V
V <sub>OL</sub>	Low-level output voltage			±5%V <sub>CC</sub>		0.30	0.50	V
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = Min, I_I = I_{IK}$		-0.73	-1.2	V	
l	Input current at maximur	n input voltage	$V_{CC} = Max, V_I = 7.0V$			100	μΑ	
I <sub>IH</sub>	High-level input current		$V_{CC} = Max, V_I = 2.7V$				20	μΑ
IIL	Low-level input current	CE	$V_{CC} = Max, V_1 = 0.5V$				-1.8	mA
		Others	$v_{\rm CC} =  v ax, v  = 0.5v$				-0.6	mA
I <sub>OS</sub>	Short-circuit output curre	nt <sup>3</sup>	V <sub>CC</sub> = Max	-60		-150	mA	
I <sub>CC</sub>	Supply current <sup>4</sup> (total)		V <sub>CC</sub> = Max		40	55	mA	

#### NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

 All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

4. Measure I<sub>CC</sub> all inputs grounded and all outputs open.

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### AC ELECTRICAL CHARACTERISTICS

					LIMIT	ſS		
SYMBOL	PARAMETER	TEST CONDITIONS	V V	<sub>amb</sub> = +25° / <sub>CC</sub> = +5.0 50pF, R <sub>L</sub> =	V	T <sub>amb</sub> = 0°C V <sub>CC</sub> = +5. C <sub>L</sub> = 50pF,	UNIT	
			Min	Тур	Max	Min	Max	
f <sub>MAX</sub>	Maximum clock frequency to Qn outputs	Waveform 1	100	125		90		MHz
f <sub>MAX</sub>	Maximum clock frequency to RC outputs	Waveform 1	85	95		75		MHz
t <sub>PLH</sub>	Propagation delay	Waveform 1	2.5	4.5	8.0	2.0	8.5	ns
t <sub>PHL</sub>	CP to Q <sub>n</sub>		5.0	7.5	11.5	5.0	12.0	ns
t <sub>PLH</sub>	Propagation delay	Waveform 1	6.5	9.0	12.5	6.0	13.0	ns
t <sub>PHL</sub>	CP to TC		6.0	8.0	11.0	6.0	12.0	ns
t <sub>PLH</sub>	Propagation delay	Waveform 2	2.5	4.5	7.5	2.0	8.0	ns
t <sub>PHL</sub>	CP to RC		3.0	5.0	7.5	2.5	8.0	ns
t <sub>PLH</sub>	Propagation delay	Waveform 2	2.0	4.0	7.0	2.0	7.5	ns
t <sub>PHL</sub>	CE to RC		3.0	5.0	7.5	3.0	8.0	ns
t <sub>PLH</sub>	Propagation delay	Waveform 2	8.0	11.0	16.0	8.0	17.0	ns
t <sub>PHL</sub>	U/D to RC		4.5	7.5	10.5	4.0	11.0	ns
t <sub>PLH</sub>	Propagation delay	Waveform 4	4.0	6.5	9.5	3.0	10.5	ns
t <sub>PHL</sub>	Ū/D to TC		3.0	6.0	9.5	3.0	10.0	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay $D_n$ to $Q_n$	Waveform 3	2.0 6.5	4.0 9.0	7.0 12.0	1.5 6.5	7.5 13.0	ns ns
t <sub>PLH</sub>	Propagation delay	Waveform 3	5.5	9.5	13.0	5.0	14.0	ns
t <sub>PHL</sub>	D <sub>n</sub> to TC	Waveform 4	6.5	9.5	13.0	6.0	14.0	ns
t <sub>PLH</sub>	Propagation delay	Waveform 3	6.0	14.0	18.0	6.0	19.5	ns
t <sub>PHL</sub>	D <sub>n</sub> to RC	Waveform 4	6.0	11.0	13.5	6.0	15.0	ns
t <sub>PLH</sub>	Propagation delay	Waveform 5	4.5	6.5	9.5	4.0	10.5	ns
t <sub>PHL</sub>	PL to Q <sub>n</sub>		5.5	8.0	11.5	5.0	12.0	ns
t <sub>PLH</sub>	Propagation delay	Waveform 5	5.5	8.5	12.0	5.5	13.0	ns
t <sub>PHL</sub>	PL to TC		6.0	10.5	13.5	6.0	14.5	ns
t <sub>PLH</sub>	Propagation delay	Waveform 5	8.5	16.0	18.5	8.5	21.0	ns
t <sub>PHL</sub>	PL to RC		7.5	10.0	13.0	7.0	13.5	ns

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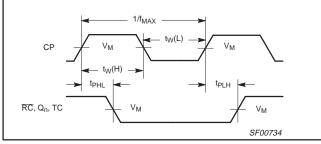
### AC SETUP REQUIREMENTS

					LIMIT	ſS		
SYMBOL	PARAMETER	TEST CONDITIONS	V	<sub>amb</sub> = +25° ′ <sub>CC</sub> = +5.0 50pF, R <sub>L</sub> =	V	T <sub>amb</sub> = 0°C V <sub>CC</sub> = +5. C <sub>L</sub> = 50pF,	UNIT	
			Min	Тур	Max	Min	Max	
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time, High or Low $D_n$ to $\overline{PL}$	Waveform 6	4.5 4.5			5.0 5.0		ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, High or Low $D_n$ to $\overline{PL}$	Waveform 6	2.0 2.0			2.0 2.0		ns ns
t <sub>s</sub> (L)	Setup time, Low CE to CP	Waveform 6	10.0			10.0		ns
t <sub>h</sub> (L)	Hold time, Low $\overline{CE}$ to CP	Waveform 6	0			0		ns
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time, High or Low $\overline{U}/D$ to CP	Waveform 6	12.0 12.0			12.0 12.0		ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, High or Low $\overline{U}/D$ to CP	Waveform 6	0 0			0 0		ns ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	CP Pulse width, High or Low	Waveform 1	3.5 6.0			3.5 6.0		ns ns
t <sub>w</sub> (L)	PL Pulse width, Low	Waveform 5	6.0			6.0		ns
t <sub>rec</sub>	Recovery time, PL to CP	Waveform 5	6.0			6.0		ns

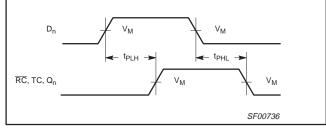
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#### AC WAVEFORMS

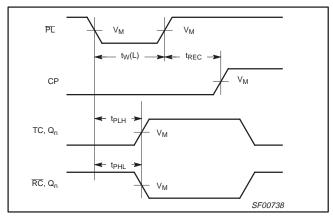
**NOTE:** For all waveforms,  $V_M = 1.5V$ 



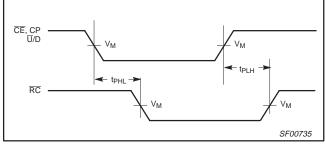




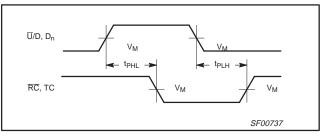
Waveform 3. Propagation Delay, Non-Inverting Path



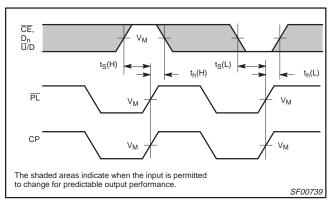
Waveform 5. Parallel Load Pulse Width, Parallel Load to Output Delay and Parallel Load to Clock Recovery Time



Waveform 2. Propagation Delay, Clock, Clock Enable or Up/Down to Ripple Clock Output



Waveform 4. Propagation Delay, Inverting Path

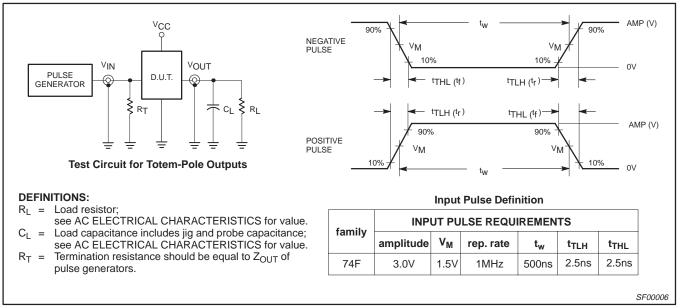


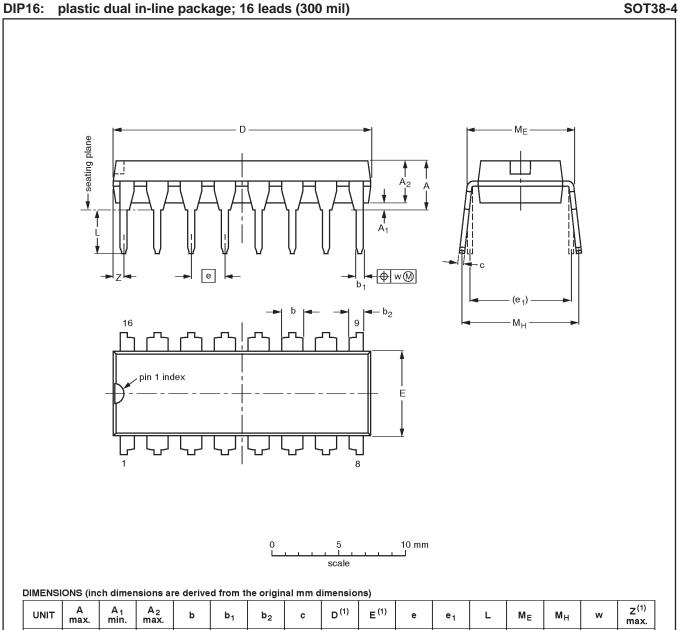
Waveform 6. Data Set Up and Hold Times

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#### **TEST CIRCUIT AND WAVEFORM**





mm     4.2     0.51     3.2     1.73 1.30     0.53 0.38     1.25 0.85     0.36 0.23     19.50 18.55     6.48 6.20     2.54     7.62     3.60 3.05     8.25 7.80     10.0 8.3     0.254     0.76       inches     0.17     0.020     0.13     0.068 0.051     0.021 0.015     0.049 0.033     0.014 0.009     0.77 0.73     0.26 0.24     0.10     0.30     0.14 0.12     0.32 0.31     0.39 0.33     0.01     0.030		max.	min.	max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D\''	E	е	e <sub>1</sub>	L	ME	MH	w	max.
	mm	4.2	0.51	3.2							2.54	7.62				0.254	0.76
	inches	0.17	0.020	0.13	1	1				1	0.10	0.30				0.01	0.030

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION		REFER	EUROPEAN	ISSUE DATE	
	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT38-4					<del>-92-11-17-</del> 95-01-14

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#### SO16: plastic small outline package; 16 leads; body width 3.9 mm SOT109-1 А D Х = v 🕅 A 16 Q A<sub>2</sub> $(A_3)$ А pin 1 index p 丗 H П 8 e $\Phi \otimes M$ detail X bp 0 2.5 5 mm scale DIMENSIONS (inch dimensions are derived from the original mm dimensions) Α D<sup>(1)</sup> E<sup>(1)</sup> Z<sup>(1)</sup> A<sub>2</sub> ${\rm H}_{\rm E}$ UNIT $A_1$ $A_3$ bp С L Q w θ е Lp v У max. 10.0 4.0 0.7 0.25 1.45 0.49 0.25 6.2 1.0 0.7 1.27 1.05 0.25 0.25 mm 1.75 0.25 0.1 8° 0.10 1.25 0.36 0.19 9.8 3.8 5.8 0.4 0.6 0.3 00 0.028 0.010 0.057 0.019 0.0100 0.39 0.16 0.244 0.039 0.028 0.050 0.041 inches 0.069 0.01 0.01 0.01 0.004 0.004 0.049 0.014 0.0075 0.38 0.15 0.228 0.016 0.020 0.012 Note 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included. REFERENCES OUTLINE EUROPEAN **ISSUE DATE** PROJECTION VERSION IEC JEDEC EIAJ 95-01-23 SOT109-1 076E07S MS-012AC $\odot$ E

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NOTES

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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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Document order number:

print code

Date of release: 10-98 9397-750-05093

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